**Product data sheet** 

# 1. General description

Dual P-channel enhancement mode Field-Effect Transistor (FET) in a leadless ultra small DFN1010B-6 (SOT1216) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 2. Features and benefits

- · Low threshold voltage
- Very fast switching
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection typically > 2 kV HBM

## 3. Applications

- · Relay driver
- · High-speed line driver
- · High-side load switch
- · Switching circuits

## 4. Quick reference data

#### Table 1. Quick reference data

| Symbol            | Parameter                        | Conditions   |     | Min | Тур | Max   | Unit |
|-------------------|----------------------------------|--|-----|-----|-----|-------|------|
| $V_{DS}$          | drain-source voltage             | T <sub>j</sub> = 25 °C   |     | -   | -   | -20   | V    |
| $V_{GS}$          | gate-source voltage              |  |     | -8  | =   | 8     | V    |
| I <sub>D</sub>    | drain current                    | V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C                   | [1] | -   | -   | -0.57 | Α    |
|                   |                                  | $V_{GS}$ = -4.5 V; $T_{sp}$ = 25 °C                                  |     | -   | =   | -2.3  | Α    |
| Static characte   | Static characteristics           |  |     |     |     |       |      |
| R <sub>DSon</sub> | drain-source on-state resistance | $V_{GS} = -4.5 \text{ V}; I_D = -1.2 \text{ A}; T_j = 25 \text{ °C}$ |     | -   | 590 | 770   | mΩ   |

<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.



# 5. Pinning information

**Table 2. Pinning information** 

| Pin | Symbol | Description | Simplified outline   | Graphic symbol     |
|-----|--------|-------------|----------------------|--------------------|
| 1   | S1     | source TR1  |                      |                    |
| 2   | G1     | gate TR1    | 1 (7 6               | D1 D2              |
| 3   | D2     | drain TR2   |                      |                    |
| 4   | S2     | source TR2  | [2] [5]              | G1 $G2$ $G2$       |
| 5   | G2     | gate TR2    | 3 8 4                |                    |
| 6   | D1     | drain TR1   |                      | 14 12              |
| 7   | D1     | drain TR1   | Transparent top view | S1 S2<br>017aaa260 |
| 8   | D2     | drain TR2   | DFN1010B-6 (SOT1216) |                    |

# 6. Ordering information

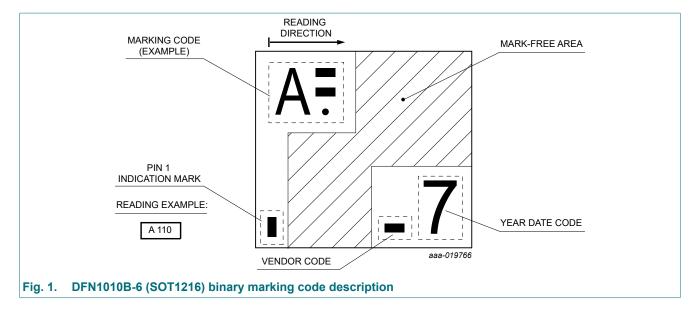
**Table 3. Ordering information** 

| Type number | Package |   |         |  |  |
|-------------|---------|---|---------|--|--|
|             | Name    | Description   | Version |  |  |
| PMDXB590UPE |         | plastic, leadless thermal enhanced ultra thin small outline package; 6 terminals; 0.35 mm pitch; 1.1 mm x 1 mm x 0.37 mm body | SOT1216 |  |  |

# 7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMDXB590UPE | D            |
|             | 010          |



# 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol           | Parameter               | Conditions  |     | Min | Max   | Unit |
|------------------|-------------------------|---|-----|-----|-------|------|
| V <sub>DS</sub>  | drain-source voltage    | T <sub>j</sub> = 25 °C                              |     | -   | -20   | V    |
| V <sub>GS</sub>  | gate-source voltage     |   |     | -8  | 8     | V    |
| I <sub>D</sub>   | drain current           | V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C  | [1] | -   | -0.57 | Α    |
|                  |                         | V <sub>GS</sub> = -4.5 V; T <sub>sp</sub> = 25 °C   |     | -   | -2.3  | Α    |
|                  |                         | V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 100 °C | [1] | -   | -0.36 | Α    |
|                  |                         | V <sub>GS</sub> = -4.5 V; T <sub>sp</sub> = 100 °C  |     | -   | -1.5  | Α    |
| I <sub>DM</sub>  | peak drain current      | $T_{amb}$ = 25 °C; single pulse; $t_p \le 10 \mu s$ |     | -   | -9.2  | Α    |
| P <sub>tot</sub> | total power dissipation | T <sub>amb</sub> = 25 °C                            | [2] | -   | 280   | mW   |
|                  |                         |   | [1] | -   | 370   | mW   |
|                  |                         | T <sub>sp</sub> = 25 °C                             |     | -   | 6     | W    |
| Tj               | junction temperature    |   |     | -55 | 150   | °C   |
| T <sub>amb</sub> | ambient temperature     |   |     | -55 | 150   | °C   |
| T <sub>stg</sub> | storage temperature     |   |     | -65 | 150   | °C   |
| Source-drai      | n diode                 |   | '   | '   | '     | ,    |
| Is               | source current          | T <sub>amb</sub> = 25 °C                            | [1] | -   | -0.34 | Α    |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.
- [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

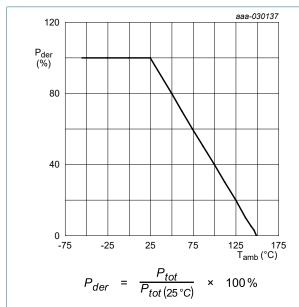


Fig. 2. Normalized total power dissipation as a function of ambient temperature

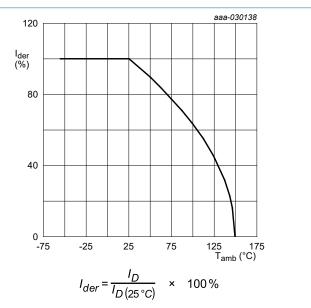


Fig. 3. Normalized continuous drain current as a function of ambient temperature

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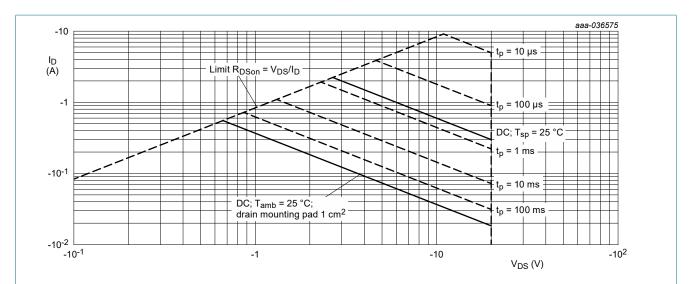


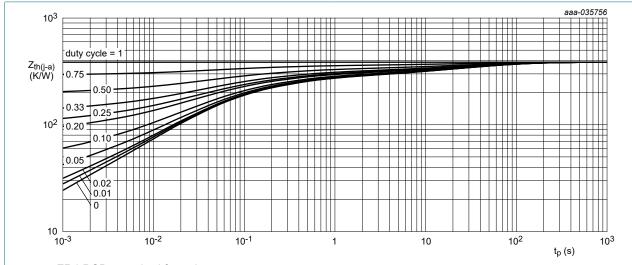
Fig. 4. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

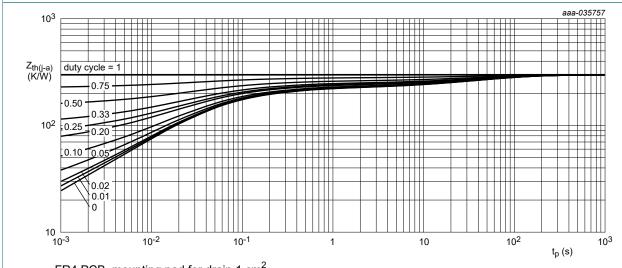
| Symbol               | Parameter  | Conditions  |     | Min | Тур | Max | Unit |
|----------------------|--|-------------|-----|-----|-----|-----|------|
| R <sub>th(j-a)</sub> | thermal resistance from                          | in free air | [1] | -   | 386 | 444 | K/W  |
| junction to ambient  | junction to ambient                              |             | [2] | -   | 297 | 342 | K/W  |
| $R_{th(j-sp)}$       | thermal resistance from junction to solder point |             |     | -   | 18  | 21  | K/W  |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm<sup>2</sup>.



FR4 PCB, standard footprint

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for drain 1 cm<sup>2</sup>

Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

# 10. Characteristics

#### Table 7. Characteristics

| Symbol               | Parameter                         | Conditions  | Min   | Тур  | Max  | Unit     |
|----------------------|-----------------------------------|---|-------|------|------|----------|
| Static chara         | acteristics                       |   |       |      |      |          |
| V <sub>(BR)DSS</sub> | drain-source<br>breakdown voltage | $I_D$ = -250 $\mu$ A; $V_{GS}$ = 0 V; $T_j$ = 25 °C                         | -20   | -    | -    | V        |
| $V_{GSth}$           | gate-source threshold voltage     | $I_D$ = -250 $\mu$ A; $V_{DS}$ = $V_{GS}$ ; $T_j$ = 25 °C                   | -0.45 | -0.7 | -1   | V        |
| I <sub>DSS</sub>     | drain leakage current             | V <sub>DS</sub> = -20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C      | -     | -    | -1   | μΑ       |
|                      |                                   | V <sub>DS</sub> = -20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 150 °C     | -     | -    | -20  | μΑ       |
| I <sub>GSS</sub>     | gate leakage current              | $V_{GS} = -8 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$          | -     | -    | -10  | μΑ       |
|                      |                                   | V <sub>GS</sub> = 8 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C        | -     | -    | 10   | μΑ       |
|                      |                                   | $V_{GS} = -4.5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$        | -     | -    | -1   | μΑ       |
|                      |                                   | V <sub>GS</sub> = 4.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C      | -     | -    | 1    | μΑ       |
|                      |                                   | $V_{GS} = -2.5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$        | -     | -    | -500 | nA       |
|                      |                                   | V <sub>GS</sub> = 2.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C      | -     | -    | 500  | nA       |
| Doon                 | drain-source on-state             | $V_{GS} = -4.5 \text{ V}; I_D = -1.2 \text{ A}; T_j = 25 \text{ °C}$        | -     | 590  | 770  | mΩ       |
|                      | resistance                        | $V_{GS} = -4.5 \text{ V}; I_D = -1.2 \text{ A}; T_j = 150 ^{\circ}\text{C}$ | -     | 890  | 1200 | mΩ       |
|                      |                                   | $V_{GS}$ = -2.5 V; $I_D$ = -1 A; $T_j$ = 25 °C                              | -     | 980  | 1400 | mΩ       |
|                      |                                   | $V_{GS}$ = -1.8 V; $I_D$ = -120 mA; $T_j$ = 25 °C                           | -     | 1170 | 1970 | mΩ       |
| 9 <sub>fs</sub>      | forward transconductance          | $V_{DS} = -5 \text{ V}; I_D = -0.6 \text{ A}; T_j = 25 \text{ °C}$          | -     | 1.2  | -    | S        |
| Dynamic ch           | naracteristics                    |   |       | '    |      | <u>'</u> |
| Q <sub>G(tot)</sub>  | total gate charge                 | V <sub>DS</sub> = -10 V; I <sub>D</sub> = -0.6 A; V <sub>GS</sub> = -4.5 V; | -     | 0.6  | 8.0  | nC       |
| Q <sub>GS</sub>      | gate-source charge                | T <sub>j</sub> = 25 °C  | -     | 0.1  | -    | nC       |
| Q <sub>GD</sub>      | gate-drain charge                 |   | -     | 0.1  | -    | nC       |
| C <sub>iss</sub>     | input capacitance                 | V <sub>DS</sub> = -10 V; f = 1 MHz; V <sub>GS</sub> = 0 V;                  | -     | 53.5 | -    | pF       |
| C <sub>oss</sub>     | output capacitance                | T <sub>j</sub> = 25 °C  | -     | 9.6  | -    | pF       |
| C <sub>rss</sub>     | reverse transfer capacitance      |   | -     | 7.8  | -    | pF       |
| t <sub>d(on)</sub>   | turn-on delay time                | $V_{DS}$ = -10 V; $I_{D}$ = -1.2 A; $V_{GS}$ = -4.5 V;                      | -     | 1    | -    | ns       |
| t <sub>r</sub>       | rise time                         | $R_{G(ext)} = 6 \Omega; T_j = 25 °C$  | -     | 3    | -    | ns       |
| t <sub>d(off)</sub>  | turn-off delay time               |   | -     | 6    | -    | ns       |
| t <sub>f</sub>       | fall time                         | 1   | -     | 3.7  | -    | ns       |
| Source-dra           | in diode                          |   | '     |      |      |          |
| $V_{SD}$             | source-drain voltage              | $I_S = -0.34 \text{ A}; V_{GS} = 0 \text{ V}; T_i = 25 ^{\circ}\text{C}$    | -     | -0.9 | -1.2 | V        |

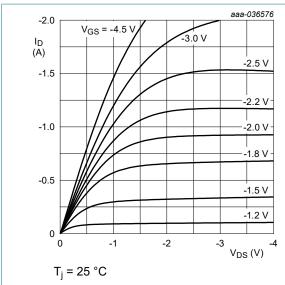


Fig. 7. Output characteristics: drain current as a function of drain-source voltage; typical values

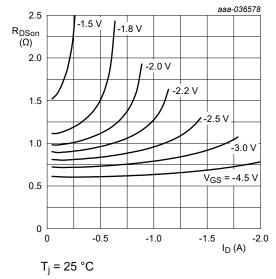


Fig. 9. Drain-source on-state resistance as a function of drain current; typical values

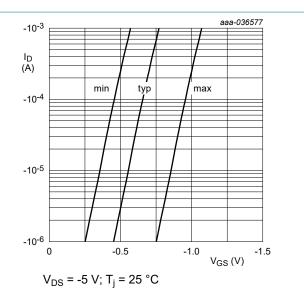


Fig. 8. Sub-threshold drain current as a function of gate-source voltage

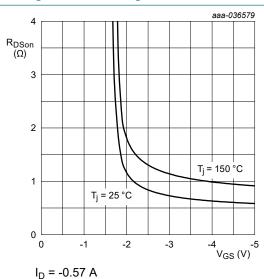


Fig. 10. Drain-source on-state resistance as a function of gate-source voltage; typical values

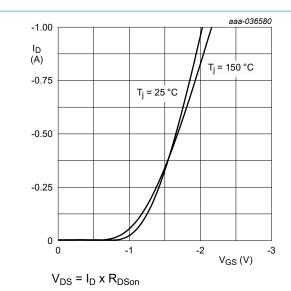


Fig. 11. Transfer characteristics: drain current as a function of gate-source voltage; typical values

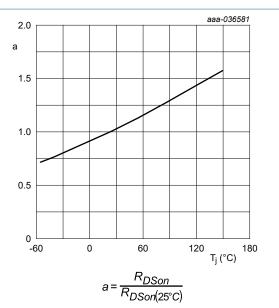


Fig. 12. Normalized drain-source on-state resistance as a function of junction temperature; typical values

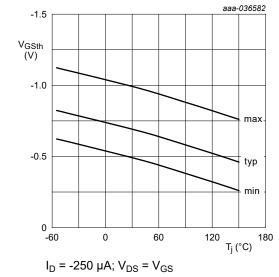
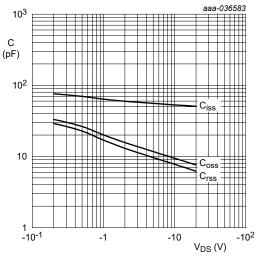


Fig. 13. Gate-source threshold voltage as a function of junction temperature



 $f = 1 MHz; V_{GS} = 0 V$ 

Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

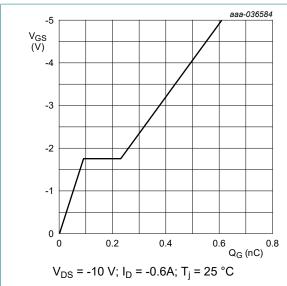


Fig. 15. Gate-source voltage as a function of gate charge; typical values

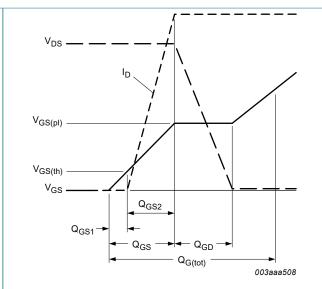


Fig. 16. Gate charge waveform definitions

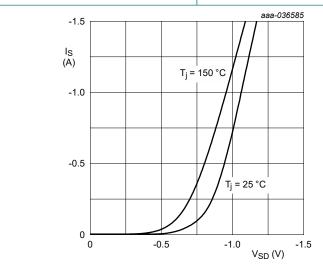
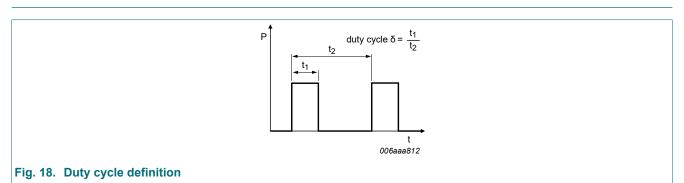


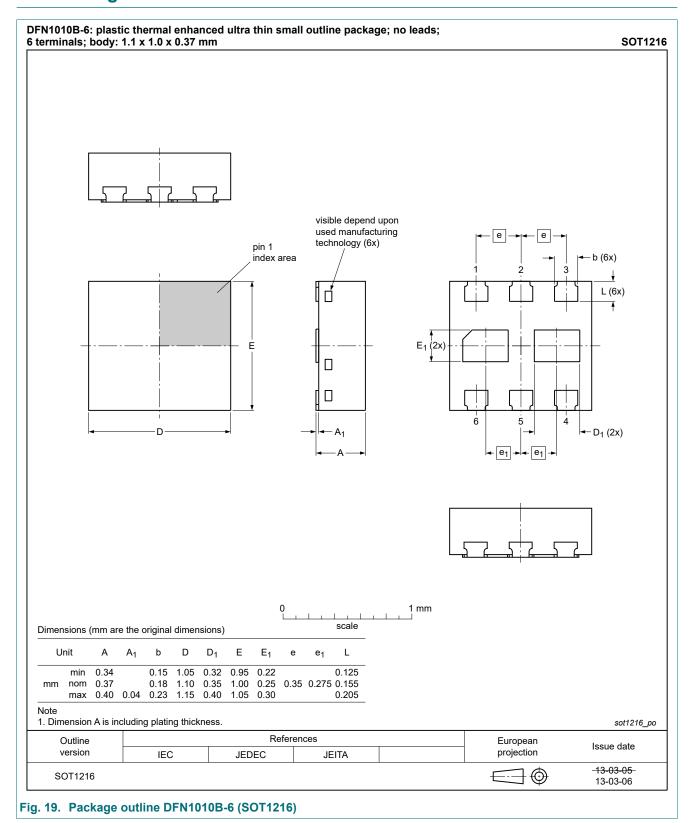
Fig. 17. Source current as a function of source-drain voltage; typical values

## 11. Test information

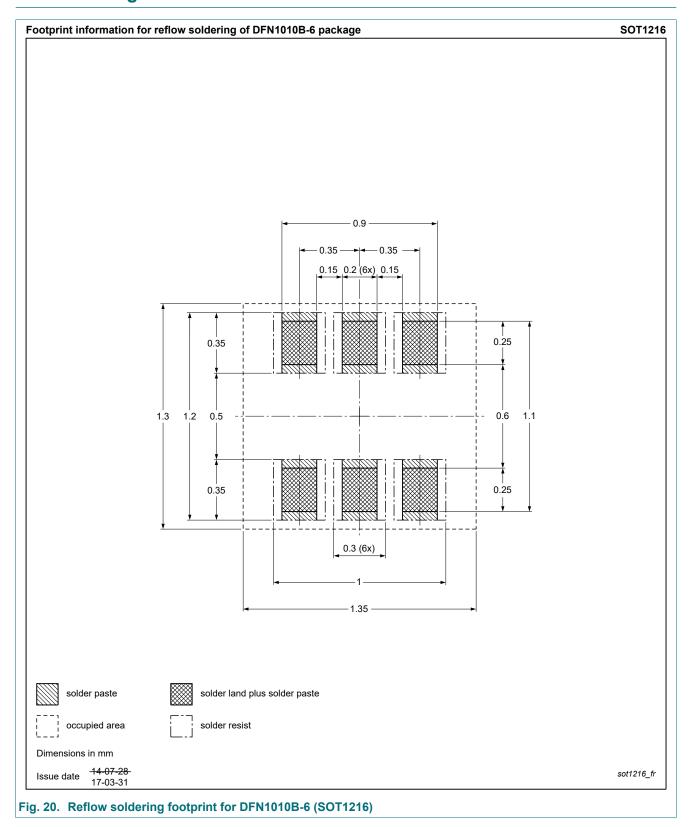
 $V_{GS} = 0 V$ 



# 12. Package outline



# 13. Soldering



# 14. Revision history

### **Table 8. Revision history**

| Data sheet ID   | Release date | Data sheet status  | Change notice | Supersedes |
|-----------------|--------------|--------------------|---------------|------------|
| PMDXB590UPE v.1 | 20230530     | Product data sheet | -             | -          |

## 15. Legal information

#### **Data sheet status**

| Document status [1][2]         | Product<br>status [3] | Definition  |
|--------------------------------|-----------------------|---|
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- Please consult the most recently issued document before initiating or completing a design.
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For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 30 May 2023

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